CMOS Digital Integrated Circuit Silicon Monolithic

# TC9590XBG

Automotive Peripheral Devices

### Overview

TC9590XBG is a bridge device that converts HDMI<sup>®</sup> stream to MIPI<sup>®</sup> CSI-2 <sup>SM</sup> TX.

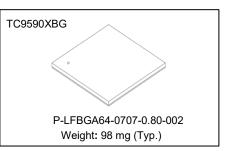
The current and next generation Application Processors for automotive have been designed without video streaming input port except CSI-2 for Camcorder input.

TC9590XBG takes in HDMI input and converts to CSI-2 that looks like a Camcorder input.

### Features

- HDMI-RX Interface
  - ♦ HDMI 1.4a
  - Video Formats Support (Up to 1080P @60fps)
  - > RGB, YCbCr444: 24-bpp @60fps
  - > YCbCr422 24-bpp @60fps
  - Audio Support
    - Internal Audio PLL to track N/CTS value transmitted by the ACR packet.
  - 3D Support
  - Supports HDCP (optional)
  - DDC Support
  - EDID Support
    - Release A, Revision 1 (Feb 9, 2000)
    - First 128 byte (EDID 1.3 structure)
    - First E-EDID Extension: 128 bytes of CEA Extension version 3 (specified in CEA-861-D)
  - Embedded 1K-byte SRAM (EDID\_SRAM)
  - Maximum HDMI clock speed: 165 MHz
- ♦ Does not support Audio Return Path and HDMI Ethernet Channels
- CSI-2 TX Interface
  - ♦ MIPI CSI-2 compliant (Version 1.01 Revision 0.04 – 2 April 2009)
- Supports up to 1 Gbps per data lane
   Video, Audio and InfoFrame data can be transmit over MIPI CSI-2
- $\diamond$  Supports up to 4 data lanes
- I<sup>2</sup>C Slave Interface
- ♦ Supports Ultra Fast-mode (2 MHz)
- ♦ Configures all TC9590XBG internal registers

- Audio Output Interface Either I2S or TDM Audio interface available (pins are multiplexed)
  - 12S Audio Interface
  - $\diamond$  Single data lane for stereo data
- ♦ Supports Master Clock mode only
- $\diamond$  Supports Left or Right-justify with MSB first
- ♦ Supports 32 bit-wide time-slot only
- ♦ Outputs Audio Oversampling clock (256fs)
- TDM (Time Division Multiplexed) Audio Interface
- Fixed to 8 channels (depend on HDMI input stream)
- Supports 32 bit-wide time slot only
- Supports Master Clock mode only
- ♦ Supports 16, 18, 20 or 24-bit PCM audio data word (depend on HDMI input stream)
- ♦ Outputs Audio Oversampling clock (256fs)
- InfraRed (IR)
  - ♦ Supports NEC Infrared protocol
- System
- ♦ Internal core has two power domains (VDDC1 and VDDC2)
- VDDC1 is always on power domain
- VDDC2 can be shut-off during deep sleep mode
- Power supply inputs
  - ♦ Core and MIPI D-PHY: 1.2 V
- ♦ I/O: 1.8V or 3.3 V
- ♦ HDMI: 3.3 V
- ♦ APLL: 2.5 V
- Power Consumption during typical operations
- ♦ 1080P @30fps: 0.48 W
- ♦ 1080P @60fps: 0.54 W



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#### REFERENCES

- 1. MIPI D-PHY, "MIPI\_D-PHY\_specification\_v01-00-00, May 14, 2009"
- 2. MIPI CSI-2, "MIPI Alliance Standard for Camera Serial Interface 2 (CSI-2) Version 1.01 Revision Nov 2010"
- 3. VESA Mobile Display Digital Interface Standard (Version 1.2, Type II)
- 4. I<sup>2</sup>C bus specification, version 2.1, January 2000, Philips Semiconductor
- 5. HDMI, "High-Definition Multimedia Interface Specification Version 1.4a March 4, 2010"

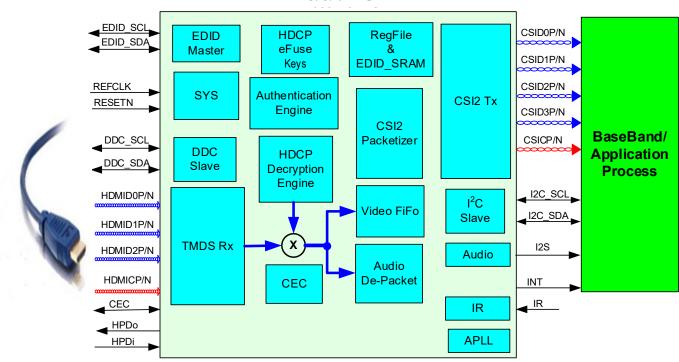
## 1. Overview

TC9590XBG is a bridge device that converts HDMI stream to MIPI CSI-2 TX.

The current and next generation Application Processors for automotive have been designed without video streaming input port except CSI-2 for Camcorder input.

TC9590XBG takes in HDMI input and converts to CSI-2 that looks like a Camcorder input.

TC9590XBG System Overview block diagram is shown below.



TC9590XBG

Figure 1.1 TC9590XBG System Overview

### 2. Features

Below are the main features supported by TC9590XBG.

- HDMI-RX Interface
  - ♦ HDMI 1.4a
    - Video Formats Support (Up to 1080P @60fps)
      - > RGB, YCbCr444: 24-bpp @60fps
      - YCbCr422 24-bpp @60fps
    - Audio Support
      - > Internal Audio PLL to track N/CTS value transmitted by the ACR packet.
    - 3D Support
    - Supports HDCP (optional)
    - DDC Support
    - EDID Support
      - Release A, Revision 1 (Feb 9, 2000)
      - First 128 byte (EDID 1.3 structure)
      - > First E-EDID Extension: 128 bytes of CEA Extension version 3 (specified in CEA-861-D)
      - Embedded 1K-byte SRAM (EDID\_SRAM)
    - Maximum HDMI clock speed: 165 MHz
  - ♦ Does not support Audio Return Path and HDMI Ethernet Channels
- CSI-2 TX Interface
  - ♦ MIPI CSI-2 compliant (Version 1.01 Revision 0.04 2 April 2009)
  - $\diamond$  Supports up to 1 Gbps per data lane
    - Video, Audio and InfoFrame data can be transmit over MIPI CSI-2
  - ♦ Supports up to 4 data lanes
- I<sup>2</sup>C Slave Interface
  - ♦ Supports for Normal-mode (100 kHz) and Fast-mode (400 kHz)
  - ♦ Supports Ultra Fast-mode (2 MHz)
  - ♦ Configures all TC9590XBG internal registers
- Audio Output Interface

Either I2S or TDM Audio interface available (pins are multiplexed) I2S Audio Interface

- ♦ Single data lane for stereo data
- ♦ Supports Master Clock mode only
- ♦ Supports 16, 18, 20 or 24-bit data (depend on HDMI input stream)
- ♦ Supports Left or Right-justify with MSB first
- ♦ Supports 32 bit-wide time-slot only
- ♦ Outputs Audio Oversampling clock (256fs)

#### TDM (Time Division Multiplexed) Audio Interface

- ♦ Fixed to 8 channels (depend on HDMI input stream)
- $\diamond$  Supports 32 bit-wide time slot only
- ♦ Supports Master Clock mode only
- ♦ Supports 16, 18, 20 or 24-bit PCM audio data word (depend on HDMI input stream)

- ♦ Outputs Audio Oversampling clock (256fs)
- InfraRed (IR)
  - ♦ Supports NEC Infrared protocol
- System
  - ♦ Internal core has two power domains (VDDC1 and VDDC2)
    - VDDC1 is always on power domain
    - VDDC2 can be shut-off during deep sleep mode
- Power supply inputs
  - ♦ Core and MIPI D-PHY: 1.2 V
  - ♦ I/O: 1.8 V or 3.3 V
  - ♦ HDMI: 3.3 V
  - ♦ APLL: 2.5 V
- Power Consumption during typical operations
  - ♦ 720P @60fps: 0.48 W
  - ♦ 1080P @30fps: 0.48 W
  - ♦ 1080P @60fps: 0.54 W

		<b>VDDC1</b> 1.2	<b>VDDC2</b>	<b>VDDIO1</b> 3.3	<b>VDDIO2</b> 1.8	VDDMIPI 1.2	AVDD33 3.3	AVDD12 1.2	AVDD25	Total Power	Unit
720P	720P (A)		472	0	0.0009	0.0178	0.0879	0.0656	0.0128		
@60fps	Power (W)	0.05	664	0	0.0017	0.0214	0.2901	0.0787	0.032	480.47	mW
1080P	Current (A)	0.0	766	0	0.0009	0.0228	0.0881	0.0829	0.0128	- 543.19 mW	
@60fps	Power (W)	0.09	9192	0	0.0017	0.0274	0.2907	0.0995	0.032		mv
Sleep	Current (µA)	0.	91	0.002	0.0430	0.0490	32.3700	0.3200	0.2	108.94	u\\/
0x0002 = 0x0001	Power (µW)	1.0	92	0.0066	0.0774	0.0588	106.8210	0.3840	0.5	100.94	μW

Table 2.1 TC9590XBG Power Consumption during typical operations

Note:

- TC9590XBG does not perform YCbCr  $\leftrightarrow$  YUV conversion. In this document they are used interchangeably.
- TC9590XBG is provided with and without HDCP keys. They are identified with package mark shown below.
  - Figure 2.1, indicates HDCP keys are burned into the device.
  - Figure 2.2, shows HDCP key is not included, please ignore all the registers field related to HDCP functionality.







Figure 2.2 Package Marking without HDCP Key, HNL is appended to weekly code

# 3. External Pins

TC9590XBG resides in BGA64 pin packages. The following table gives the signals of TC9590XBG and their function.

Group	Pin Name	I/O	Init (O)	Туре	Function	Voltage Supply	Note
	RESETN	Ι	-	Sch	System reset input, active low	VDDIO2	1.8V or 3.3V
System: Reset &	REFCLK	I	-	Ν	Reference clock input (27/26 MHz or 42 MHz)	VDDIO2	1.8V or 3.3V
Clock (4)	TEST	Ι	-	Ν	TEST mode select 0: Normal mode 1: Test mode	VDDIO2	1.8V or3.3V
	INT	0	L	N	Interrupt Output signal – active high (Level)	VDDIO2	1.8V or 3.3V
	CSICP	-	Н	MIPI-PHY	MIPI-CSI-2 clock positive	VDD_MIPI	1.2V
	CSICN	-	Н	MIPI-PHY	MIPI-CSI-2 clock negative	VDD_MIPI	1.2V
	CSID0P	-	Н	MIPI-PHY	MIPI-CSI-2 Data 0 positive	VDD_MIPI	1.2V
	CSID0N	-	Н	MIPI-PHY	MIPI-CSI-2 Data 0 negative	VDD_MIPI	1.2V
CSI-2 TX	CSID1P	-	Н	MIPI-PHY	MIPI-CSI-2 Data 1 positive	VDD_MIPI	1.2V
(10)	CSID1N	-	Н	MIPI-PHY	MIPI-CSI-2 Data 1 negative	VDD_MIPI	1.2V
	CSID2P	-	Н	MIPI-PHY	MIPI-CSI-2 Data 2 positive	VDD_MIPI	1.2V
	CSID2N	-	Н	MIPI-PHY	MIPI-CSI-2 Data 2 negative	VDD_MIPI	1.2V
	CSID3P	-	Н	MIPI-PHY	MIPI-CSI-2 Data 3 positive	VDD_MIPI	1.2V
	CSID3N	-	Н	MIPI-PHY	MIPI-CSI-2 Data 3 negative	VDD_MIPI	1.2V
	HDMICP	-	-		HDMI Clock channel positive	AVDD33	3.3V
	HDMICN	-	-	HDMI-PHY	HDMI Clock channel negative	AVDD33	3.3V
	HDMID0P	-	-	HDMI-PHY	HDMI Data 0 channel positive	AVDD33	3.3V
HDMI-RX	HDMID0N	-	-	HDMI-PHY	HDMI Data 0 channel negative	AVDD33	3.3V
(8)	HDMID1P	-	-		HDMI Data 1 channel positive	AVDD33	3.3V
	HDMID1N	-	-		HDMI Data 1 channel negative	AVDD33	3.3V
	HDMID2P	-	-			AVDD33	3.3V
	HDMID2N	-	-	HDMI-PHY	HDMI Data 2 channel negative	AVDD33	3.3V
DDC	DDC_SCL	10	-	N (Note2)	DDC Slave Clock	VDDIO1	3.3V (Note1)
(2)	DDC_SDA	0	-	N (Note2)	DDC Slave data	VDDIO1	3.3V (Note1)
EDID	EDID_SCL	10	-	N (Note2)	EDID Master Clock	VDDIO2	1.8V or 3.3V
(2)	EDID_SDA	10	-		EDID Master Data	VDDIO2	1.8V or 3.3V
CEC	CEC	10	-	N (Note2)	CEC signal	VDDIO1	3.3V
HPD	HPDI	1	-	N	Hot Plug Detect Input	VDDIO1	3.3V (Note1)
(2)	HPDO	0	L	N	Hot Plug Detect Output	VDDIO1	3.3V
	A_SCK	0	L	Ν	I2S/TDM Bit Clock signal	VDDIO2	1.8V or 3.3V
Audio	A_WFS	0	L	Ν	I2S Word Clock or TDM Frame Sync signal	VDDIO2	1.8V or 3.3V
(4)	A_SD	0	L	Ν	I2S/TDM data signal	VDDIO2	1.8V or 3.3V
	A_OSCK	0	L	Ν	Audio Oversampling Clock	VDDIO2	1.8V or 3.3V
IR	IR	Ι	-	Sch	Infrared signal	VDDIO2	1.8V or 3.3V
12C	I2C_SCL	10	-	N (Note2)	I <sup>2</sup> C serial clock	VDDIO2	1.8V or 3.3V
(2)	I2C_SDA	ю	-	N <sup>(Note2)</sup>	I <sup>2</sup> C serial data	VDDIO2	1.8V or 3.3V
APLL (4)	BIASDA	0	L	-	BIAS signal Connect to AVSS through 0.1µF when not used	-	-
(+)	DAOUT	0	Н	-	Audio PLL clock Reference Output clock Please leave open when not used	-	-

Table 3.1 TC9590XBG Functional Signal Lis	Table 3.1	TC9590XBG Functional Signal List
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Group	Pin Name	I/O	Init (O)	Туре	Function	Voltage Supply	Note
	PCKIN	I	-	-	Audio PLL Reference Input clock Connect to AVSS through 0.1µF when not used	-	-
	PFIL	0	L	-	<ul> <li>Audio PLL Low Pass Filter signal</li> <li>Connect to AVSS through 0.1µF when not used</li> </ul>		-
	VDDC1, VDDC2	-	-	-	VDD for Internal Core (3)	-	1.2V
	VDDIO1	-	-	-	VDDIO1 IO power supply (1)	-	3.3V
POWER	VDDIO2	-	-	-	VDDIO2 IO power supply (1)	-	1.8V or 3.3V
(12) VDD MIF	VDD_MIPI	-	-	-	VDD for the MIPI CSI-2 (2)	-	1.2V
	AVDD12	-	-	-	HDMI PHY 1.2 V power supply (2)	-	1.2V
	AVDD33	I	-	-	HDMI PHY 3.3 V power supply (2)	-	3.3V
	AVDD25	•	-	-	APLL 2.5 V power supply (1)	-	2.5V
Ground (10)	VSS	-	-	-	Ground	-	-
Misc	REXT	-	-	-	External Reference Resistor, Please connect to AVDD33 with a 2 $k\Omega$ resistor (± 1%)	-	-
(2)	VPGM	-	-	-	eFuse program power supply, please tie to ground	-	-

Total 64 pins

Note1: These IO are 5 V tolerant. Note2: Bi-directional IO with Schmitt trigger input.

#### **Buffer Type Abbreviation:**

N:	Normal IO
N <sub>PD</sub> :	Normal IO with weak Internal Pull-Down
N <sub>PU</sub> :	Normal IO with weak Internal Pull-Up
FS-SOD:	Failed Safe Pseudo open-drain output, Schmitt input
FS:	Failed Safe IO
Sch: MIPI-PHY: HDMI-PHY:	Schmitt input buffer front-end analog IO for CSI-2 front-end analog IO for HDMI

### 3.1. TC9590XBG BGA64 Pin Count Summary

Table 5.2 BGA04 FILLO	
Group Name	Pin Count
System	4
CSI-2 TX	10
HDMI-RX	8
DDC	2
EDID	2
CEC	1
HPD	2
Audio	4
IR	1
I2C	2
APLL	4
POWER	12
Ground	10
Misc	2
TOTAL	64

#### Table 3.2 BGA64 Pin Count Summary

### 3.2. Pin Layout

A1	A2	A3	A4	A5	A6	A7	A8
REXT	VSS	VPGM	BIASDA	DAOUT	PFIL	CSID3N	CSID3P
B1	<b>B2</b>	B3	<b>B4</b>	<b>B5</b>	B6	<b>B7</b>	B8
AVDD33	AVDD12	INT	IR	AVDD25	PCKIN	CSID2N	CSID2P
C1	C2	C3	C4	C5	C6	C7	C8
HDMICP	HDMICN	VDDC2	VSS	VSS	VDD_MIPI	CSICN	CSICP
D1	D2	D3	D4	D5	D6	D7	D8
HDMID0P	HDMID0N	AVDD12	VSS	VSS	VSS	CSID1N	CSID1P
E1	E2	E3	E4	E5	E6	E7	E8
HDMID1P	HDMID1N	VSS	VSS	TEST	VSS	CSID0N	CSID0P
F1	F2	F3	F4	F5	F6	F7	<b>F8</b>
HDMID2P	HDMID2N	AVDD33	VDDIO1	VDDC2	VDD_MIPI	A_SCK	A_SD
G1	G2	G3	G4	G5	<b>G6</b>	G7	G8
CEC	VDDC1	DDC_SDA	I2C_SDA	RESETN	EDID_SDA	A_WFS	A_OSCK
H1	H2	H3	H4	H5	H6	H7	H8
HPDO	HPDI	DDC_SCL	I2C_SCL	REFCLK	EDID_SCL	VDDIO2	VSS

Figure 3.1 TC9590XBG 64-Pin Layout (Top View)

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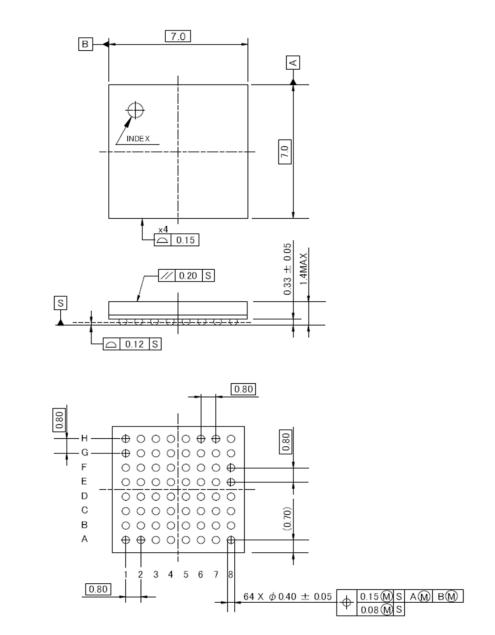
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# 4. Package

The packages for TC9590XBG are described in the figures below.

P-LFBGA64-0707-0.80-002

(Unit: mm)



Weight: 98 mg (Typ.)



Dimension	Min	Тур.	Max
Solder ball pitch	-	0.80 mm	-
Package dimension	-	7.0 × 7.0 mm <sup>2</sup>	-
Package height	-	-	1.4 mm

# **5. Electrical Characteristics**

### 5.1. Absolute Maximum Ratings

VSS = 0	V	reference
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Parameter	Symbol	Rating	Unit
Supply voltage (1.8 V - Digital IO)	VDDIO	-0.3 to +3.9	V
Supply voltage (1.2 V – Digital Core)	VDDC	-0.3 to +1.8	V
Supply voltage (1.2 V – MIPI CSI PHY)	VDD_MIPI	-0.3 to +1.8	V
Supply voltage (3.3 V – HDMIRX PHY)	AVDD33	-0.3 to +3.9	V
Supply voltage (1.2 V – HDMIRX PHY)	AVDD12	-0.3 to +1.8	V
Supply voltage (2.5 V – APLL)	AVDD25	-0.3 to AVDD25 + 0.3	V
Input voltage (CSI IO)	V <sub>IN_CSI</sub>	-0.3 to VDD_MIPI + 0.3	V
Output voltage (CSI IO)	V <sub>OUT_CSI</sub>	-0.3 to VDD_MIPI + 0.3	V
Input voltage (Digital IO)	V <sub>IN_IO</sub>	-0.3 to VDDIO + 0.3	V
Output voltage (Digital IO)	V <sub>OUT_IO</sub>	-0.3 to VDDIO + 0.3	V
Output voltage (APLL)	Vout_apll	-0.3 to AVDD25 + 0.3	V
Junction temperature	Tj	125	С°
Storage temperature	Tstg	-40 to +125	°C

### 5.2. Operating Condition

VSS = 0 V reference

Parameter	Symbol	Min	Тур.	Мах	Unit
Supply voltage (1.8/3.3 V – Digital IO)	VDDIO2	1.65	1.8	3.6	V
Supply voltage (3.3 V – HDMI Digital IO)	VDDIO1	3.0	3.3	3.6	V
Supply voltage (1.2 V – Digital Core)	VDDC	1.1	1.2	1.3	V
Supply voltage (1.2 V – MIPI CSI PHY)	VDD_MIPI	1.1	1.2	1.3	V
Supply voltage (2.5 V – APLL)	AVDD25	2.25	2.5	2.75	V
Operating temperature (ambient temperature with voltage applied)	Та	-40	25	85	°C
Supply Noise Voltage	VSN	-	-	0.1	Vpp
Supply voltage (3.3 V – HDMIRX PHY)	AVDD33	3.135	3.3	3.465	V
Supply Noise Voltage for AVDD33	VSN33	-	-	0.08	Vpp
Supply voltage (1.2 V – HDMIRX PHY)	AVDD12	1.15	1.2	1.25	V
Supply Noise Voltage for AVDD12	VSN12	-	-	0.04	Vpp

### **5.3. DC Electrical Specification**

Parameter	Symbol	Min	Тур.	Мах	Unit
Input voltage, High level input Note1	VIH	0.7 x VDDIO	-	VDDIO	V
Input voltage, Low level input Note1	VIL	0	-	0.3 x VDDIO	V
Input voltage High level CMOS Schmitt Trigger <sup>Note1,2</sup>	VIHS	0.7 x VDDIO	-	VDDIO	V
Input voltage Low level CMOS Schmitt Trigger <sup>Note1,2</sup>	V <sub>ILS</sub>	0	-	0.3 x VDDIO	V
Output voltage High level Note1, Note2	V <sub>OH</sub>	0.8 x VDDIO	-	VDDIO	V
Output voltage Low level Note1, Note2	V <sub>OL</sub>	0	-	0.2 x VDDIO	V
Input leak current, High level (Condition: V <sub>IN</sub> = VDDIO, VDDIO = 3.6 V)	I <sub>ILH1</sub> (Note4)	-10	-	10	μA
Input leak current, Low level (Condition: V <sub>IN</sub> = 0 V, VDDIO = 3.6 V)	I <sub>ILL1</sub> (Note5)	-10	-	10	μA

Note1: Each power source is operating within operation condition.

Note2: Current output value is specified to each IO buffer individually. Output voltage changes with output current value.

Note4: Normal pin or Pull-up IO pin applied VDDIO supply voltage to Vin (input voltage)

Note5: Normal pin applied VSS (0 V) to Vin (input voltage)

# 6. Revision History

Revision	Date	Description
1.0	2020-06-05	Newly released

#### Table 6.1 Revision History

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